

## EFM32LG900 DATASHEET

F256

- **ARM Cortex-M3 CPU platform**
  - High Performance 32-bit processor @ up to 48 MHz
  - Memory Protection Unit
- **Flexible Energy Management System**
  - 20 nA @ 3 V Shutoff Mode
  - 0.4 µA @ 3 V Shutoff Mode with RTC
  - 0.65 µA @ 3 V Stop Mode, including Power-on Reset, Brown-out Detector, RAM and CPU retention
  - 0.95 µA @ 3 V Deep Sleep Mode, including RTC with 32.768 kHz oscillator, Power-on Reset, Brown-out Detector, RAM and CPU retention
  - 63 µA/MHz @ 3 V Sleep Mode
  - 211 µA/MHz @ 3 V Run Mode, with code executed from flash
- **256 KB Flash**
- **32 KB RAM**
- **93 General Purpose I/O pins**
  - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
  - Configurable peripheral I/O locations
  - 16 asynchronous external interrupts
  - Output state retention and wake-up from Shutoff Mode
- **12 Channel DMA Controller**
- **12 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling**
- **Hardware AES with 128/256-bit keys in 54/75 cycles**
- **Timers/Counters**
  - 4x 16-bit Timer/Counter
    - 4x3 Compare/Capture/PWM channels
    - Dead-Time Insertion on TIMER0
  - 16-bit Low Energy Timer
  - 1x 24-bit Real-Time Counter and 1x 32-bit Real-Time Counter
  - 3x 16/8-bit Pulse Counter
  - Watchdog Timer with dedicated RC oscillator @ 50 nA
- **Integrated LCD Controller for up to 8x36 segments**
  - Voltage boost, adjustable contrast and autonomous animation
- **Backup Power Domain**
  - RTC and retention registers in a separate power domain, available in all energy modes
  - Operation from backup battery when main power drains out
- **External Bus Interface for up to 4x256 MB of external memory mapped space**
  - TFT Controller with Direct Drive
- **Communication interfaces**
  - 3x Universal Synchronous/Asynchronous Receiver/Transmitter
    - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S
  - 2x Universal Asynchronous Receiver/Transmitter
  - 2x Low Energy UART
    - Autonomous operation with DMA in Deep Sleep Mode
  - 2x I<sup>2</sup>C Interface with SMBus support
    - Address recognition in Stop Mode
  - Universal Serial Bus (USB) with Host & OTG support
    - Fully USB 2.0 compliant
    - On-chip PHY and embedded 5V to 3.3V regulator
- **Ultra low power precision analog peripherals**
  - 12-bit 1 Msamples/s Analog to Digital Converter
    - 8 single ended channels/4 differential channels
    - On-chip temperature sensor
  - 12-bit 500 ksamples/s Digital to Analog Converter
    - 2 single ended channels/1 differential channel
  - 2x Analog Comparator
    - Capacitive sensing with up to 16 inputs
  - 3x Operational Amplifier
    - 6.1 MHz GBW, Rail-to-rail, Programmable Gain
  - Supply Voltage Comparator
- **Low Energy Sensor Interface (LESENSE)**
  - Autonomous sensor monitoring in Deep Sleep Mode
  - Wide range of sensors supported, including LC sensors and capacitive buttons
- **Ultra efficient Power-on Reset and Brown-Out Detector**
- **Debug Interface**
  - 2-pin Serial Wire Debug interface
    - 1-pin Serial Wire Viewer
  - Embedded Trace Module v3.5 (ETM)
- **Pre-Programmed USB/UART Bootloader**
- **Temperature range -40 to 85 °C**
- **Single power supply 1.98 to 3.8 V**
- **Delivered as full wafer**

32-bit ARM Cortex-M0+, Cortex-M3 and Cortex-M4 microcontrollers for:

- Energy, gas, water and smart metering
- Health and fitness applications
- Smart accessories
- Alarm and security systems
- Industrial and home automation



# 1 Ordering Information

Table 1.1 (p. 2) shows the available EFM32LG900 devices.

**Table 1.1. Ordering Information**

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (°C)	Package
EFM32LG900F256G-E-D1I	256	32	48	1.98 - 3.8	-40 - 85	Wafer

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## 2 System Summary

The EFM32LG900 products are delivered in wafer form, but are otherwise identical to the EFM32LG995 packaged parts. Please refer to the EFM32LG995 datasheet for additional information.

### 3 Pinout and Package

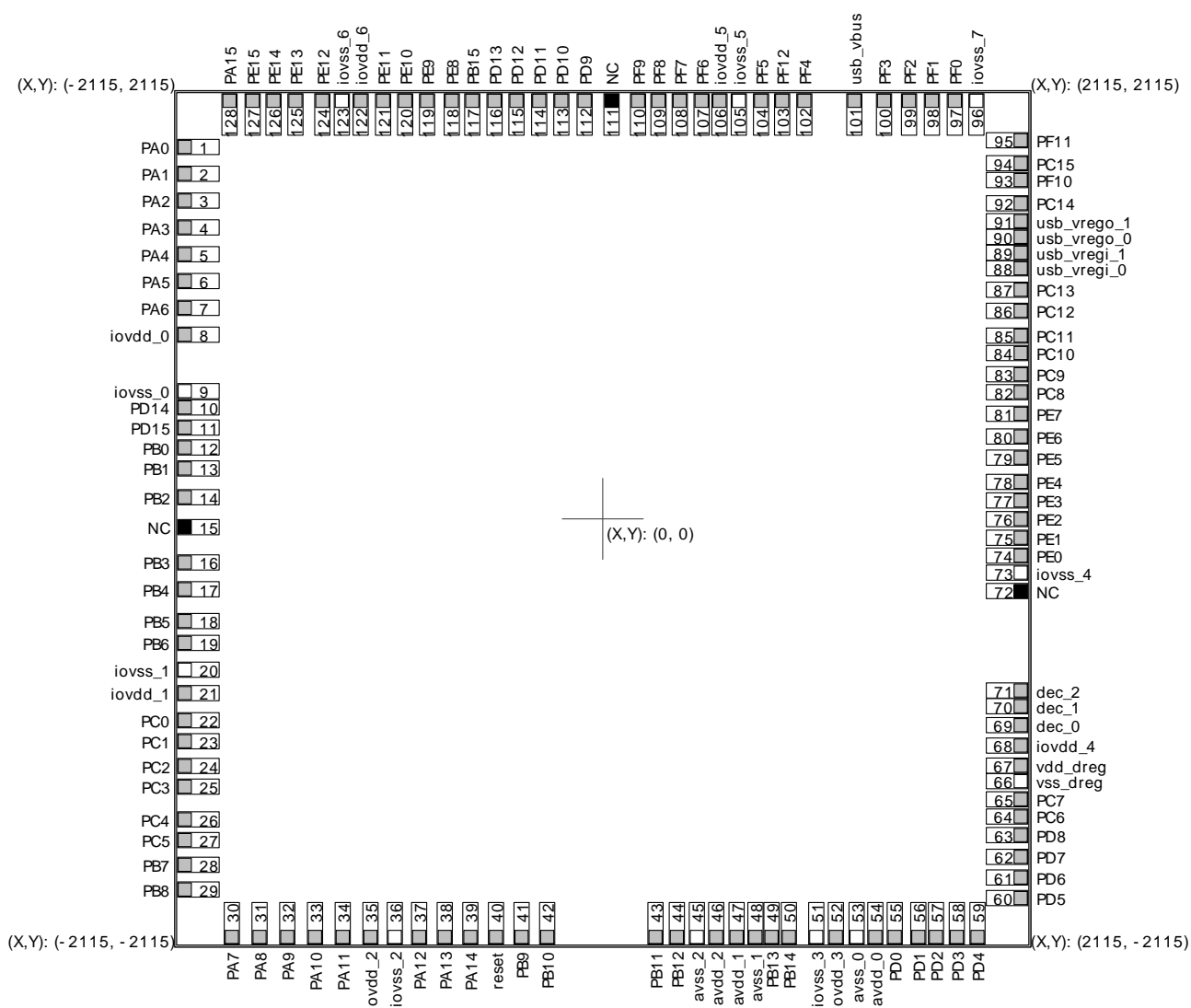
### Note

Please refer to the application note "AN0002 EFM32 Hardware Design Considerations" for guidelines on designing Printed Circuit Boards (PCB's) for the EFM32LG900.

### 3.1 Padout

The *EFM32LG900* padout is shown in Figure 3.1 (p. 4) and Table 3.1 (p. 5). Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pad are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the \*\_ROUTE register in the module in question.

**Figure 3.1. EFM32LG900 Padout (top view, not to scale)**



The pad coordinates represent the center of the pad opening relative to the die center.

Table 3.1. Device Padout

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Commu- nication	Other
1	PA0	-2065.0	1837.0	LCD_SEG13	EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
2	PA1	-2065.0	1704.6	LCD_SEG14	EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2	-2065.0	1572.1	LCD_SEG15	EBI_AD11 #0/1/2	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3
4	PA3	-2065.0	1439.7	LCD_SEG16	EBI_AD12 #0/1/2	TIM0_CDTI0 #0	U0_TX #2	LES_ALTEX2 #0 ETM_TD1 #3
5	PA4	-2065.0	1307.2	LCD_SEG17	EBI_AD13 #0/1/2	TIM0_CDTI1 #0	U0_RX #2	LES_ALTEX3 #0 ETM_TD2 #3
6	PA5	-2065.0	1174.7	LCD_SEG18	EBI_AD14 #0/1/2	TIM0_CDTI2 #0	LEU1_TX #1	LES_ALTEX4 #0 ETM_TD3 #3
7	PA6	-2065.0	1042.3	LCD_SEG19	EBI_AD15 #0/1/2		LEU1_RX #1	ETM_TCLK #3 GPIO_EM4WU1
8	IOVDD_0	-2065.0	909.8	Digital IO power supply 0.				
9	IOVSS_0	-2065.0	630.9	Digital IO ground 0.				
10	PD14	-2065.0	550.5				I2C0_SDA #3	
11	PD15	-2065.0	451.0				I2C0_SCL #3	
12	PB0	-2065.0	352.7	LCD_SEG32	EBI_A16 #0/1/2	TIM1_CC0 #2		
13	PB1	-2065.0	249.0	LCD_SEG33	EBI_A17 #0/1/2	TIM1_CC1 #2		
14	PB2	-2065.0	107.0	LCD_SEG34	EBI_A18 #0/1/2	TIM1_CC2 #2		
15	NC	-2065.0	-40.8	Do not connect.				
16	PB3	-2065.0	-215.2	LCD_SEG20/ LCD_COM4	EBI_A19 #0/1/2	PCNT1_S0IN #1	US2_TX #1	
17	PB4	-2065.0	-347.7	LCD_SEG21/ LCD_COM5	EBI_A20 #0/1/2	PCNT1_S1IN #1	US2_RX #1	
18	PB5	-2065.0	-504.7	LCD_SEG22/ LCD_COM6	EBI_A21 #0/1/2		US2_CLK #1	
19	PB6	-2065.0	-612.6	LCD_SEG23/ LCD_COM7	EBI_A22 #0/1/2		US2_CS #1	
20	IOVSS_1	-2065.0	-745.0	Digital IO ground 1.				
21	IOVDD_1	-2065.0	-860.7	Digital IO power supply 1.				
22	PC0	-2065.0	-994.8	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	EBI_A23 #0/1/2	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
23	PC1	-2065.0	-1098.4	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	EBI_A24 #0/1/2	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
24	PC2	-2065.0	-1220.4	ACMP0_CH2 DAC0_OUT0ALT #2/ OPAMP_OUT0ALT	EBI_A25 #0/1/2	TIM0_CDTI0 #4	US2_TX #0	LES_CH2 #0
25	PC3	-2065.0	-1322.6	ACMP0_CH3 DAC0_OUT0ALT #3/ OPAMP_OUT0ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
26	PC4	-2065.0	-1484.3	ACMP0_CH4 DAC0_P0 / OPAMP_P0	EBI_A26 #0/1/2	TIM0_CDTI2 #4 LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
27	PC5	-2065.0	-1586.5	ACMP0_CH5 DAC0_N0 / OPAMP_N0	EBI_NANDWEen #0/1/2	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0 I2C1_SCL #0	LES_CH5 #0

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Commu- nication	Other
28	PB7	-2065.0	-1708.6	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
29	PB8	-2065.0	-1830.6	LFXTAL_N		TIM1_CC1 #3	US0_RX #4 US1_CS #0	
30	PA7	-1832.5	-2065.0	LCD_SEG35	EBI_CSTFT #0/1/2			
31	PA8	-1695.5	-2065.0	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
32	PA9	-1558.5	-2065.0	LCD_SEG37	EBI_DTEN #0/1/2	TIM2_CC1 #0		
33	PA10	-1421.5	-2065.0	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
34	PA11	-1284.5	-2065.0	LCD_SEG39	EBI_HSNC #0/1/2			
35	IOVDD_2	-1147.5	-2065.0	Digital IO power supply 2.				
36	IOVSS_2	-1027.4	-2065.0	Digital IO ground 2.				
37	PA12	-907.2	-2065.0	LCD_BCAP_P	EBI_A00 #0/1/2	TIM2_CC0 #1		
38	PA13	-780.6	-2065.0	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
39	PA14	-654.0	-2065.0	LCD_BEXT	EBI_A02 #0/1/2	TIM2_CC2 #1		
40	RESETn	-527.4	-2065.0	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
41	PB9	-401.0	-2065.0		EBI_A03 #0/1/2		U1_TX #2	
42	PB10	-274.5	-2065.0		EBI_A04 #0/1/2		U1_RX #2	
43	PB11	260.7	-2065.0	DAC0_OUT0 / OPAMP_OUT0		TIM1_CC2 #3 LETIM0_OUT0 #1	I2C1_SDA #1	
44	PB12	366.0	-2065.0	DAC0_OUT1 / OPAMP_OUT1		LETIM0_OUT1 #1	I2C1_SCL #1	
45	AVSS_2	464.8	-2065.0	Analog ground 2.				
46	AVDD_2	560.5	-2065.0	Analog power supply 2.				
47	AVDD_1	661.2	-2065.0	Analog power supply 1.				
48	AVSS_1	754.5	-2065.0	Analog ground 1.				
49	PB13	833.8	-2065.0	HFXTAL_P			US0_CLK #4/5 LEU0_TX #1	
50	PB14	919.6	-2065.0	HFXTAL_N			US0_CS #4/5 LEU0_RX #1	
51	IOVSS_3	1054.9	-2065.0	Digital IO ground 3.				
52	IOVDD_3	1151.7	-2065.0	Digital IO power supply 3.				
53	AVSS_0	1254.2	-2065.0	Analog ground 0.				
54	AVDD_0	1346.8	-2065.0	Analog power supply 0.				
55	PD0	1442.7	-2065.0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	
56	PD1	1559.2	-2065.0	ADC0_CH1 DAC0_OUT1ALT #4/ OPAMP_OUT1ALT		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	DBG_SWO #2
57	PD2	1646.3	-2065.0	ADC0_CH2	EBI_A27 #0/1/2	TIM0_CC1 #3	USB_DMPU #0 US1_CLK #1	DBG_SWO #3
58	PD3	1749.3	-2065.0	ADC0_CH3 OPAMP_N2		TIM0_CC2 #3	US1_CS #1	ETM_TD1 #0/2
59	PD4	1851.4	-2065.0	ADC0_CH4 OPAMP_P2			LEU0_TX #0	ETM_TD2 #0/2

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Commu- nication	Other
60	PD5	2065.0	-1872.9	ADC0_CH5 OPAMP_OUT2 #0			LEU0_RX #0	ETM_TD3 #0/2
61	PD6	2065.0	-1771.3	ADC0_CH6 DAC0_P1 / OPAMP_P1		TIM1_CC0 #4 LETIM0_OUT0 #0 PCNT0_S0IN #3	US1_RX #2 I2C0_SDA #1	LES_ALTEX0 #0 ACMP0_O #2 ETM_TD0 #0
62	PD7	2065.0	-1669.4	ADC0_CH7 DAC0_N1 / OPAMP_N1		TIM1_CC1 #4 LETIM0_OUT1 #0 PCNT0_S1IN #3	US1_TX #2 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 #0 ACMP1_O #2 ETM_TCLK #0
63	PD8	2065.0	-1561.9	BU_VIN				CMU_CLK1 #1
64	PC6	2065.0	-1470.2	ACMP0_CH6	EBI_A05 #0/1/2		LEU1_TX #0 I2C0_SDA #2	LES_CH6 #0 ETM_TCLK #2
65	PC7	2065.0	-1385.2	ACMP0_CH7	EBI_A06 #0/1/2		LEU1_RX #0 I2C0_SCL #2	LES_CH7 #0 ETM_TD0 #2
66	VSS_DREG	2065.0	-1295.5	Ground for on-chip voltage regulator.				
67	VDD_DREG	2065.0	-1218.8	Power supply for on-chip voltage regulator.				
68	IOVDD_4	2065.0	-1119.8	Digital IO power supply 4.				
69	DEC_0	2065.0	-1018.9	Decouple output for on-chip voltage regulator.				
70	DEC_1	2065.0	-925.3	Decouple output for on-chip voltage regulator.				
71	DEC_2	2065.0	-847.7	Decouple output for on-chip voltage regulator.				
72	NC	2065.0	-356.4	Do not connect.				
73	IOVSS_4	2065.0	-265.5	Digital IO ground 4.				
74	PE0	2065.0	-181.4		EBI_A07 #0/1/2	TIM3_CC0 #1 PCNT0_S0IN #1	U0_TX #1 I2C1_SDA #2	
75	PE1	2065.0	-93.2		EBI_A08 #0/1/2	TIM3_CC1 #1 PCNT0_S1IN #1	U0_RX #1 I2C1_SCL #2	
76	PE2	2065.0	-1.1	BU_VOUT	EBI_A09 #0	TIM3_CC2 #1	U1_TX #3	ACMP0_O #1
77	PE3	2065.0	91.1	BU_STAT	EBI_A10 #0		U1_RX #3	ACMP1_O #1
78	PE4	2065.0	182.6	LCD_COM0	EBI_A11 #0/1/2		US0_CS #1	
79	PE5	2065.0	302.4	LCD_COM1	EBI_A12 #0/1/2		US0_CLK #1	
80	PE6	2065.0	406.9	LCD_COM2	EBI_A13 #0/1/2		US0_RX #1	
81	PE7	2065.0	519.2	LCD_COM3	EBI_A14 #0/1/2		US0_TX #1	
82	PC8	2065.0	625.8	ACMP1_CH0	EBI_A15 #0/1/2	TIM2_CC0 #2	US0_CS #2	LES_CH8 #0
83	PC9	2065.0	714.3	ACMP1_CH1	EBI_A09 #1/2	TIM2_CC1 #2	US0_CLK #2	LES_CH9 #0 GPIO_EM4WU2
84	PC10	2065.0	819.1	ACMP1_CH2	EBI_A10 #1/2	TIM2_CC2 #2	US0_RX #2	LES_CH10 #0
85	PC11	2065.0	905.1	ACMP1_CH3	EBI_ALE #1/2		US0_TX #2	LES_CH11 #0
86	PC12	2065.0	1027.7	ACMP1_CH4 DAC0_OUT1ALT #0/ OPAMP_OUT1ALT			U1_TX #0	CMU_CLK0 #1 LES_CH12 #0
87	PC13	2065.0	1131.8	ACMP1_CH5 DAC0_OUT1ALT #1/ OPAMP_OUT1ALT		TIM0_CDTI0 #1/3 TIM1_CC0 #0 TIM1_CC2 #4 PCNT0_S0IN #0	U1_RX #0	LES_CH13 #0
88	USB_VREGI_0	2065.0	1237.6	USB input to internal 3.3 V regulator.				
89	USB_VREGI_1	2065.0	1314.6	USB input to internal 3.3 V regulator.				
90	USB_VREGO_0	2065.0	1393.0	USB decoupling for internal 3.3 V USB regulator and regulator output.				
91	USB_VREGO_1	2065.0	1470.4	USB decoupling for internal 3.3 V USB regulator and regulator output.				

Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Commu- nication	Other
92	PC14	2065.0	1558.7	ACMP1_CH6 DAC0_OUT1ALT #2/ OPAMP_OUT1ALT		TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 U0_TX #3	LES_CH14 #0
93	PF10	2065.0	1673.6				U1_TX #1 USB_DM	
94	PC15	2065.0	1756.6	ACMP1_CH7 DAC0_OUT1ALT #3/ OPAMP_OUT1ALT		TIM0_CDTI2 #1/3 TIM1_CC2 #0	US0_CLK #3 U0_RX #3	LES_CH15 #0 DBG_SWO #1
95	PF11	2065.0	1870.0				U1_RX #1 USB_DP	
96	IOVSS_7	1846.0	2065.0	Digital IO ground 7.				
97	PF0	1739.3	2065.0			TIM0_CC0 #5 LETIM0_OUT0 #2	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0/1/2/3
98	PF1	1626.3	2065.0			TIM0_CC1 #5 LETIM0_OUT1 #2	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0/1/2/3 GPIO_EM4WU3
99	PF2	1513.2	2065.0	LCD_SEG0	EBI_ARDY #0/1/2	TIM0_CC2 #5	LEU0_TX #4	ACMP1_O #0 DBG_SWO #0 GPIO_EM4WU4
100	PF3	1389.7	2065.0	LCD_SEG1	EBI_ALE #0	TIM0_CDTI0 #2/5		PRS_CH0 #1 ETM_TD3 #1
101	USB_VBUS	1242.9	2065.0	USB 5.0 V VBUS input.				
102	PF4	995.9	2065.0	LCD_SEG2	EBI_WEn #0/2	TIM0_CDTI1 #2/5		PRS_CH1 #1
103	PF12	886.3	2065.0				USB_ID	
104	PF5	782.2	2065.0	LCD_SEG3	EBI_REn #0/2	TIM0_CDTI2 #2/5	USB_VBUSEN #0	PRS_CH2 #1
105	IOVSS_5	672.3	2065.0	Digital IO ground 5.				
106	IOVDD_5	576.7	2065.0	Digital IO power supply 5.				
107	PF6	488.4	2065.0	LCD_SEG24	EBI_BL0 #0/1/2	TIM0_CC0 #2	U0_TX #0	
108	PF7	380.5	2065.0	LCD_SEG25	EBI_BL1 #0/1/2	TIM0_CC1 #2	U0_RX #0	
109	PF8	275.3	2065.0	LCD_SEG26	EBI_WEn #1	TIM0_CC2 #2		ETM_TCLK #1
110	PF9	174.3	2065.0	LCD_SEG27	EBI_REn #1			ETM_TD0 #1
111	NC	43.2	2065.0	Do not connect.				
112	PD9	-89.5	2065.0	LCD_SEG28	EBI_CS0 #0/1/2			
113	PD10	-204.5	2065.0	LCD_SEG29	EBI_CS1 #0/1/2			
114	PD11	-313.8	2065.0	LCD_SEG30	EBI_CS2 #0/1/2			
115	PD12	-426.2	2065.0	LCD_SEG31	EBI_CS3 #0/1/2			
116	PD13	-534.7	2065.0					ETM_TD1 #1
117	PB15	-644.6	2065.0					ETM_TD2 #1
118	PE8	-745.8	2065.0	LCD_SEG4	EBI_AD00 #0/1/2	PCNT2_S0IN #1		PRS_CH3 #1
119	PE9	-867.9	2065.0	LCD_SEG5	EBI_AD01 #0/1/2	PCNT2_S1IN #1		
120	PE10	-976.1	2065.0	LCD_SEG6	EBI_AD02 #0/1/2	TIM1_CC0 #1	US0_TX #0	BOOT_TX
121	PE11	-1085.3	2065.0	LCD_SEG7	EBI_AD03 #0/1/2	TIM1_CC1 #1	US0_RX #0	LES_ALTEX5 #0 BOOT_RX
122	IOVDD_6	-1196.1	2065.0	Digital IO power supply 6.				
123	IOVSS_6	-1289.0	2065.0	Digital IO ground 6.				
124	PE12	-1385.4	2065.0	LCD_SEG8	EBI_AD04 #0/1/2	TIM1_CC2 #1	US0_RX #3	CMU_CLK1 #2



Wafer Pads and Coordinates				Pad Alternate Functionality / Description				
Pad #	Pad Name	X [μm]	Y [μm]	Analog	EBI	Timers	Commu- nication	Other
							US0_CLK #0 I2C0_SDA #6	LES_ALTEX6 #0
125	PE13	-1518.2	2065.0	LCD_SEG9	EBI_AD05 #0/1/2		US0_TX #3 US0_CS #0 I2C0_SCL #6	LES_ALTEX7 #0 ACMP0_O #0 GPIO_EM4WU5
126	PE14	-1626.4	2065.0	LCD_SEG10	EBI_AD06 #0/1/2	TIM3_CC0 #0	LEU0_TX #2	
127	PE15	-1729.6	2065.0	LCD_SEG11	EBI_AD07 #0/1/2	TIM3_CC1 #0	LEU0_RX #2	
128	PA15	-1844.0	2065.0	LCD_SEG12	EBI_AD08 #0/1/2	TIM3_CC2 #0		

## 3.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in Table 3.2 (p. 9). The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

### Note

Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

**Table 3.2. Alternate functionality overview**

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2	PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12							Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13							Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14							Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15							Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3	PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7							Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11							Bootloader RX.
BOOT_TX	PE10							Bootloader TX.
BU_STAT	PE3							Backup Power Domain status, whether or not the system is in backup mode
BU_VIN	PD8							Battery input for Backup Power Domain
BU_VOUT	PE2							Power output for Backup Power Domain
CMU_CLK0	PA2	PC12	PD7					Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8	PE12					Clock Management Unit, clock output number 1.
DAC0_N0 / OPAMP_N0	PC5							Operational Amplifier 0 external negative input.
DAC0_N1 / OPAMP_N1	PD7							Operational Amplifier 1 external negative input.
OPAMP_N2	PD3							Operational Amplifier 2 external negative input.
DAC0_OUT0 / OPAMP_OUT0	PB11							Digital to Analog Converter DAC0_OUT0 / OPAMP output channel number 0.
DAC0_OUT0ALT / OPAMP_OUT0ALT	PC0	PC1	PC2	PC3	PD0			Digital to Analog Converter DAC0_OUT0ALT / OPAMP alternative output for channel 0.
DAC0_OUT1 / OPAMP_OUT1	PB12							Digital to Analog Converter DAC0_OUT1 / OPAMP output channel number 1.
DAC0_OUT1ALT / OPAMP_OUT1ALT	PC12	PC13	PC14	PC15	PD1			Digital to Analog Converter DAC0_OUT1ALT / OPAMP alternative output for channel 1.
OPAMP_OUT2	PD5	PD0						Operational Amplifier 2 output.
DAC0_P0 / OPAMP_P0	PC4							Operational Amplifier 0 external positive input.
DAC0_P1 / OPAMP_P1	PD6							Operational Amplifier 1 external positive input.
OPAMP_P2	PD4							Operational Amplifier 2 external positive input.
DBG_SWCLK	PF0	PF0	PF0	PF0				Debug-interface Serial Wire clock input.  Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1	PF1	PF1				Debug-interface Serial Wire data input / output.  Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15	PD1	PD2				Debug-interface Serial Wire viewer Output.  Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_A00	PA12	PA12	PA12					External Bus Interface (EBI) address output pin 00.
EBI_A01	PA13	PA13	PA13					External Bus Interface (EBI) address output pin 01.
EBI_A02	PA14	PA14	PA14					External Bus Interface (EBI) address output pin 02.
EBI_A03	PB9	PB9	PB9					External Bus Interface (EBI) address output pin 03.
EBI_A04	PB10	PB10	PB10					External Bus Interface (EBI) address output pin 04.
EBI_A05	PC6	PC6	PC6					External Bus Interface (EBI) address output pin 05.
EBI_A06	PC7	PC7	PC7					External Bus Interface (EBI) address output pin 06.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_A07	PE0	PE0	PE0					External Bus Interface (EBI) address output pin 07.
EBI_A08	PE1	PE1	PE1					External Bus Interface (EBI) address output pin 08.
EBI_A09	PE2	PC9	PC9					External Bus Interface (EBI) address output pin 09.
EBI_A10	PE3	PC10	PC10					External Bus Interface (EBI) address output pin 10.
EBI_A11	PE4	PE4	PE4					External Bus Interface (EBI) address output pin 11.
EBI_A12	PE5	PE5	PE5					External Bus Interface (EBI) address output pin 12.
EBI_A13	PE6	PE6	PE6					External Bus Interface (EBI) address output pin 13.
EBI_A14	PE7	PE7	PE7					External Bus Interface (EBI) address output pin 14.
EBI_A15	PC8	PC8	PC8					External Bus Interface (EBI) address output pin 15.
EBI_A16	PB0	PB0	PB0					External Bus Interface (EBI) address output pin 16.
EBI_A17	PB1	PB1	PB1					External Bus Interface (EBI) address output pin 17.
EBI_A18	PB2	PB2	PB2					External Bus Interface (EBI) address output pin 18.
EBI_A19	PB3	PB3	PB3					External Bus Interface (EBI) address output pin 19.
EBI_A20	PB4	PB4	PB4					External Bus Interface (EBI) address output pin 20.
EBI_A21	PB5	PB5	PB5					External Bus Interface (EBI) address output pin 21.
EBI_A22	PB6	PB6	PB6					External Bus Interface (EBI) address output pin 22.
EBI_A23	PC0	PC0	PC0					External Bus Interface (EBI) address output pin 23.
EBI_A24	PC1	PC1	PC1					External Bus Interface (EBI) address output pin 24.
EBI_A25	PC2	PC2	PC2					External Bus Interface (EBI) address output pin 25.
EBI_A26	PC4	PC4	PC4					External Bus Interface (EBI) address output pin 26.
EBI_A27	PD2	PD2	PD2					External Bus Interface (EBI) address output pin 27.
EBI_AD00	PE8	PE8	PE8					External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	PE9	PE9	PE9					External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	PE10	PE10	PE10					External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	PE11	PE11	PE11					External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	PE12	PE12	PE12					External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	PE13	PE13	PE13					External Bus Interface (EBI) address and data input / output pin 05.
EBI_AD06	PE14	PE14	PE14					External Bus Interface (EBI) address and data input / output pin 06.
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0	PA0	PA0					External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.

Alternate	LOCATION							Description
Functionality	0	1	2	3	4	5	6	
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEn	PF4	PF8	PF4					External Bus Interface (EBI) Write Enable output.
ETM_TCLK	PD7	PF8	PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6	PF9	PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3	PD13	PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4	PB15	PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5	PF3	PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFX TAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFX TAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7	PD15	PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6	PD14	PC0	PF0	PE12	I2C0 Serial Data input / output.
I2C1_SCL	PC5	PB12	PE1					I2C1 Serial Clock Line input / output.
I2C1_SDA	PC4	PB11	PE0					I2C1 Serial Data input / output.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_BCAP_N	PA13							LCD voltage booster (optional), boost capacitor, negative pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.
LCD_BCAP_P	PA12							LCD voltage booster (optional), boost capacitor, positive pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.
LCD_BEXT	PA14							LCD voltage booster (optional), boost output. If using the LCD voltage booster, connect a 1 uF capacitor between this pin and VSS.  An external LCD voltage may also be applied to this pin if the booster is not enabled.  If AVDD is used directly as the LCD supply voltage, this pin may be left unconnected or used as a GPIO.
LCD_COM0	PE4							LCD driver common line number 0.
LCD_COM1	PE5							LCD driver common line number 1.
LCD_COM2	PE6							LCD driver common line number 2.
LCD_COM3	PE7							LCD driver common line number 3.
LCD_SEG0	PF2							LCD segment line 0. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG1	PF3							LCD segment line 1. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG2	PF4							LCD segment line 2. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG3	PF5							LCD segment line 3. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG4	PE8							LCD segment line 4. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG5	PE9							LCD segment line 5. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG6	PE10							LCD segment line 6. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG7	PE11							LCD segment line 7. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG8	PE12							LCD segment line 8. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG9	PE13							LCD segment line 9. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG10	PE14							LCD segment line 10. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG11	PE15							LCD segment line 11. Segments 8, 9, 10 and 11 are controlled by SEGEN2.
LCD_SEG12	PA15							LCD segment line 12. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG13	PA0							LCD segment line 13. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG14	PA1							LCD segment line 14. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG15	PA2							LCD segment line 15. Segments 12, 13, 14 and 15 are controlled by SEGEN3.
LCD_SEG16	PA3							LCD segment line 16. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG17	PA4							LCD segment line 17. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG18	PA5							LCD segment line 18. Segments 16, 17, 18 and 19 are controlled by SEGEN4.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LCD_SEG19	PA6							LCD segment line 19. Segments 16, 17, 18 and 19 are controlled by SEGEN4.
LCD_SEG20/ LCD_COM4	PB3							LCD segment line 20. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 4
LCD_SEG21/ LCD_COM5	PB4							LCD segment line 21. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 5
LCD_SEG22/ LCD_COM6	PB5							LCD segment line 22. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 6
LCD_SEG23/ LCD_COM7	PB6							LCD segment line 23. Segments 20, 21, 22 and 23 are controlled by SEGEN5. This pin may also be used as LCD COM line 7
LCD_SEG24	PF6							LCD segment line 24. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG25	PF7							LCD segment line 25. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG26	PF8							LCD segment line 26. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG27	PF9							LCD segment line 27. Segments 24, 25, 26 and 27 are controlled by SEGEN6.
LCD_SEG28	PD9							LCD segment line 28. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG29	PD10							LCD segment line 29. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG30	PD11							LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12							LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0							LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1							LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2							LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7							LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8							LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9							LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10							LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11							LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LES_ALTEX0	PD6							LESENSE alternate exite output 0.
LES_ALTEX1	PD7							LESENSE alternate exite output 1.
LES_ALTEX2	PA3							LESENSE alternate exite output 2.
LES_ALTEX3	PA4							LESENSE alternate exite output 3.
LES_ALTEX4	PA5							LESENSE alternate exite output 4.
LES_ALTEX5	PE11							LESENSE alternate exite output 5.
LES_ALTEX6	PE12							LESENSE alternate exite output 6.
LES_ALTEX7	PE13							LESENSE alternate exite output 7.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LES_CH0	PC0							LESENSE channel 0.
LES_CH1	PC1							LESENSE channel 1.
LES_CH2	PC2							LESENSE channel 2.
LES_CH3	PC3							LESENSE channel 3.
LES_CH4	PC4							LESENSE channel 4.
LES_CH5	PC5							LESENSE channel 5.
LES_CH6	PC6							LESENSE channel 6.
LES_CH7	PC7							LESENSE channel 7.
LES_CH8	PC8							LESENSE channel 8.
LES_CH9	PC9							LESENSE channel 9.
LES_CH10	PC10							LESENSE channel 10.
LES_CH11	PC11							LESENSE channel 11.
LES_CH12	PC12							LESENSE channel 12.
LES_CH13	PC13							LESENSE channel 13.
LES_CH14	PC14							LESENSE channel 14.
LES_CH15	PC15							LESENSE channel 15.
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0	PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1	PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2	PC0	PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3	PC1	PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0	PF6	PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	PC0	PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	PC1	PF2		Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	PC2	PF3		Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14	PC3	PF4		Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	PC4	PF5		Timer 0 Complimentary Deat Time Insertion channel 2.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
TIM1_CC0	PC13	PE10	PB0	PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11	PB1	PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2	PB11	PC13			Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8					Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9					Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10					Timer 2 Capture Compare input / output channel 2.
TIM3_CC0	PE14	PE0						Timer 3 Capture Compare input / output channel 0.
TIM3_CC1	PE15	PE1						Timer 3 Capture Compare input / output channel 1.
TIM3_CC2	PA15	PE2						Timer 3 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15				UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14				UART0 Transmit output. Also used as receive input in half duplex communication.
U1_RX	PC13	PF11	PB10	PE3				UART1 Receive input.
U1_TX	PC12	PF10	PB9	PE2				UART1 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9	PC15	PB13	PB13		USART0 clock input / output.
US0_CS	PE13	PE4	PC8	PC14	PB14	PB14		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10	PE12	PB8	PC1		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11	PE13	PB7	PC0		USART0 Asynchronous Transmit. Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2	PF0					USART1 clock input / output.
US1_CS	PB8	PD3	PF1					USART1 chip select input / output.
US1_RX	PC1	PD1	PD6					USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0	PD7					USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5						USART2 clock input / output.
US2_CS	PC5	PB6						USART2 chip select input / output.
US2_RX	PC3	PB4						USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3						USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
USB_DM	PF10							USB D- pin.
USB_DMPU	PD2							USB D- Pullup control.
USB_DP	PF11							USB D+ pin.
USB_ID	PF12							USB ID pin. Used in OTG mode.
USB_VBUS	USB_VBUS							USB 5 V VBUS input.



Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
USB_VBUSEN	PF5							USB 5 V VBUS enable.
USB_VREGI	USB_VREGI							USB Input to internal 3.3 V regulator
USB_VREGO	USB_VREGO							USB Decoupling for internal 3.3 V USB regulator and regulator output

## 3.3 GPIO Pinout Overview

The specific GPIO pins available in *EFM32LG900* is shown in Table 3.3 (p. 17). Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

**Table 3.3. GPIO Pinout**

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	-	-	-	PF12	PF11	PF10	PF9	PF8	PF7	PF6	PF5	PF4	PF3	PF2	PF1	PF0

## 3.4 Bonding Instructions

All pads should be bonded out, with the exception of the pads labeled “NC” and listed as “Do not connect” in Table 3.1 (p. 5). Gold bond wires are recommended for these devices.

All three voltage regulator output decouple pads (DEC\_0, DEC\_1, DEC\_2) must be bonded out and electrically connected on the PCB. In the packaged devices, these three pads are all bonded to a single DECOUPLE pin.

If the USB feature of EFM32LG900 will be used, all of the USB pads must be bonded out, and

- both USB\_VREGO\_0 and USB\_VREGO\_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB\_VREGO pin.
- both USB\_VREGI\_0 and USB\_VREGI\_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB\_VREGI pin.

## 3.5 Wafer Description

**Table 3.4. Wafer and Die Information**

Parameter	Value
Device Family	EFM32LG (Leopard Gecko)
Wafer Diameter	8 in
Die Dimensions (Outer edge of seal ring)	4230 $\mu$ m $\times$ 4230 $\mu$ m
Wafer Thickness (No backgrind)	725 $\mu$ m $\pm$ 15 $\mu$ m (28.54 mil $\pm$ 1 mil)
Wafer Identification	Notch
Scribe Street Width	80 $\mu$ m $\times$ 160 $\mu$ m
Die Per Wafer <sup>1</sup>	Contact sales for information
Passivation	Standard
Wafer Packaging Detail	Wafer Jar
Bond Pad Dimensions	65 $\mu$ m (parallel to die edge) $\times$ 66 $\mu$ m
Bond Pad Pitch Minimum	76 $\mu$ m
Maximum Processing Temperature	250°C
Electronic Die Map Format	.txt

<sup>1</sup>Note: This is the Expected Known Good Die yielded per wafer and represents the batch order quantity (one wafer).

### 3.5.1 Environmental

Bare silicon die are susceptible to mechanical damage and may be sensitive to light. When bare die must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

For additional Quality and Environmental information, please see:  
<http://www.silabs.com/support/quality/pages/default.aspx>.

## 3.6 Wafer Storage Guidelines

It is necessary to conform to appropriate wafer storage practices to avoid product degradation or contamination.

- Wafers may be stored for up to 18 months in the original packaging supplied by Silicon Labs.
- Wafers must be stored at a temperature of 18 - 24 °C.
- Wafers must be stored in a humidity-controlled environment with a relative humidity of <30%
- Wafers should be stored in a clean, dry, inert atmosphere (e.g. nitrogen or clean, dry air).

## 3.7 Failure Analysis (FA) Guidelines

Certain conditions must be met for Silicon Laboratories to perform Failure Analysis on devices sold in wafer form.

- In order to conduct failure analysis on a device in a customer-provided package, Silicon Laboratories must be provided with die assembled in an industry standard package that is pin compatible with existing packages Silicon Laboratories offers for the device. Initial response time for FA requests that meet these requirements will follow the standard FA guidelines for packaged parts.

- If retest of the entire wafer is requested, Silicon Laboratories must be provided with the whole wafer. Silicon Laboratories cannot retest any wafers that have been sawed, diced, backgrind or are on tape. Initial response time for FA requests that meet these requirements will be 3 weeks.

## 4 Chip Marking, Revision and Errata

### 4.1 Errata

Please see the errata document for EFM32LG900 for description and resolution of device erratas. This document is available in Simplicity Studio and online at:

<http://www.silabs.com/support/pages/document-library.aspx?p=MCUs--32-bit>

## 5 Revision History

### 5.1 Revision 1.20

March 16th, 2015

Corrected pad numbers and the order of the pads in the padout table so that it matches the drawing.

### 5.2 Revision 1.10

December 12th, 2014

Added recommendation to use gold bond wire.

### 5.3 Revision 1.00

October 15th, 2014

Initial release.

## A Disclaimer and Trademarks

### A.1 Disclaimer

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## B Contact Information

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Please visit the Silicon Labs Technical Support web page:

<http://www.silabs.com/support/pages/contacttechnicalsupport.aspx>

and register to submit a technical support request.

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